IPC ASSOCIATION ELECTRONICS	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both This docum level parts,	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Mater					ials and Mfg Information			
upplier	Information													
Company name*				Company unique ID			Unique ID Authority				Response Date*			
nsemi										2023-06-08				
ontact Na	nme		Title - Contact			Phone - Contact*				Email - Contact*				
?roduct-E	nv-Stewards		Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*		Title - Representative			Phone - Representative*			Email - Representative*					
roduct-E	nv-Stewards		Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Mfr Item	Number	Mfr Item Name		Effective Da	te Version	n N	Manufacturing Site	We	eight*	UOM	Unit Type	
		LB1867M-TLM-H 2PH DRV SENSO with hall sensor m		2PH DRV SENSOF with hall sensor me	R NA; Two phase driver thod (no speed control)	2023-06-08		РНМ		130	0.0	mg	Each	
	turing Proccess Inforn													
	Terminal Plating / Grid Array Material Termina			rminal Base Alloy J-STD-020 MSL Rating		Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles					
contains Bi		CU Alloy 3			260 C 30		30	seconds 3						
omments														
<u> TENTI</u>	ON: MSL 3 Rated item requi	ires Bake and D	ry Pack (afte	r electrical test)										
or more ii	nformation regarding materi	ial composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.81	mg	Supplier	Silicon (Si)	7440-21-3		4.7744	mg
			Supplier	Polyimide	Proprietary Data		0.0356	mg
Die Attach	0.4	mg	Supplier	Silver (Ag)	7440-22-4		0.306	mg
			Supplier	Epoxy resins	129915-35-1		0.094	mg
Lead Frame	15.4		Supplier	Zinc (Zn)	7440-66-6		0.0293	mg
			Supplier	Iron (Fe)	7439-89-6		0.3989	mg
			Supplier	Copper (Cu)	7440-50-8		14.9503	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0216	mg
Mold Compound-Black	107.34			Epoxy Phenol Resin	proprietary data		11.8074	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.8397	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		46.1562	mg
Plating	1.72	mg	В	Bismuth (Bi)	7440-69-9		0.0103	mg
			Supplier	Tin (Sn)	7440-31-5		1.7097	mg
Wire Bond - Au	0.33	mg	Supplier	Gold (Au)	7440-57-5		0.33	mg